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TITLE : EPOXY RESIN COMPOSITION FOR SEALING SEMICONDUCTOR

ABSTRACT : PURPOSE: To obtain a heat shock-and solder crack-resistant cured product having a good storage stability by using a microcapsuled latent curing catalyst having a reaction start temperature higher than a specific temperature.

CONSTITUTION: A microcapsuled latent curing catalyst having a reaction start temperature of 100°C or more is used to start the reaction of an epoxy resin with a curing agent. Hence, it will not lose the latent property even if the epoxy resin composition heats over 100°C in a kneading step. Accordingly, the composition will not lose the storage stability. This allows a high temperature kneading step to be adopted, hence the amount of a filler to increase and the shock resistance to be improved.

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